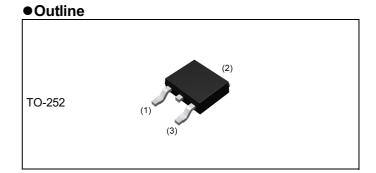


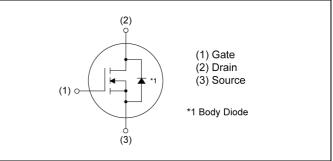
R6010MND3

Nch 600V 10A Power MOSFET

V _{DSS}	600V
R _{DS(on)} (Max.)	0.380Ω
Ι _D	±10A
P _D	143W



Inner circuit



Packaging specifications

	Packing	Embossed Tape
	Reel size (mm)	330
Туре	Tape width (mm)	16
	Basic ordering unit (pcs)	2500
	Taping code	TL
	Marking	R6010M

Application

Features

be ±30V.

2) Low on-resistance.

3) Fast switching speed.

1) Fast reverse recovery time (trr).

5) Drive circuits can be simple.6) Pb-free plating ; RoHS compliant

4) Gate-source voltage (V_{GSS}) guaranteed to

Switching Power Supply

• Absolute maximum ratings (T_a = 25°C ,unless otherwise specified)

5 (a)	, , ,		
Parameter	Symbol	Value	Unit
Drain - Source voltage	V _{DSS}	600	V
Continuous drain current ($T_c = 25^{\circ}C$)	I _D *1	±10	А
Pulsed drain current	۱ _{DP} *2	±30	A
Gate - Source voltage	V _{GSS}	±30	V
Avalanche current, single pulse	I _{AS}	1.5	А
Avalanche energy, single pulse	E _{AS} *3	0.6	mJ
Power dissipation $(T_c = 25^{\circ}C)$	P _D	143	W
Junction temperature	Tj	150	°C
Operating junction and storage temperature range	T _{stg}	-55 to +150	°C

•Thermal resistance

Deremeter	Cumph of	Values			Lincit
Parameter	Symbol	Min.	Тур.	Max.	Unit
Thermal resistance, junction - case	R_{thJC}^{*4}	-	-	0.86	°C/W
Thermal resistance, junction - ambient	R _{thJA}	-	-	100	°C/W
Soldering temperature, wavesoldering for 10s	T _{sold}	-	-	265	°C

•Electrical characteristics (T_a = 25°C)

Parameter	Sumbol	Conditions	Values			Unit	
Parameter	Symbol	Conditions	Min.	Тур.	Max.	Unit	
Drain - Source breakdown voltage	$V_{(BR)DSS}$ $V_{GS} = 0V, I_D = 1mA$		600	-	-	V	
		V _{DS} = 600V, V _{GS} = 0V					
Zero gate voltage drain current	I _{DSS}	$T_j = 25^{\circ}C$	-	-	100	μA	
		$T_j = 125^{\circ}C$	-	-	-		
Gate - Source leakage current	I _{GSS}	V_{GS} = ±30V, V_{DS} = 0V	-	-	±100	nA	
Gate threshold voltage	$V_{GS(th)}$	V _{DS} = 10V, I _D = 160µA	3.0	-	5.0	V	
		V _{GS} = 10V, I _D = 5A					
Static drain - source on - state resistance	$R_{DS(on)}^{*3}$	$T_j = 25^{\circ}C$	-	0.280	0.380	Ω	
		$T_j = 125^{\circ}C$	-	-	-		
Gate resistance	R _G	f = 1MHz, open drain	-	2.5	-	Ω	



•Electrical characteristics (T_a = 25°C)

Devenuetor	C: make al	Conditions	Values			Unit	
Parameter	Symbol	Conditions	Min.	Тур.	Max.	Unit	
Forward Transfer Admittance	$ Y_{fs} ^{*3}$ V _{DS} = 10V, I _D = 5A		3.5	-	-	S	
Input capacitance	C _{iss}	V _{GS} = 0V	-	1000	-		
Output capacitance	C _{oss}	V _{DS} = 25V	-	900	-	pF	
Reverse transfer capacitance	C _{rss}	f = 1MHz	-	12	-		
Turn - on delay time	t _{d(on)} *3	$V_{DD} \simeq 300$ V, V_{GS} = 10V	-	25	-		
Rise time	t _r *3	I _D = 5A	-	25	-	20	
Turn - off delay time	t _{d(off)} *3	$R_L \simeq 60.4\Omega$	-	40	-	ns	
Fall time	t _f *3	R _G = 10Ω	-	25	-		

• Gate charge characteristics (T_a = 25°C)

Deremeter	Cump of	Conditions	Values			Linit
Parameter	Symbol	Conditions	Min.	Тур.	Max.	Unit
Total gate charge	Q _g *3	V _{DD} ≃ 300V	-	20	-	
Gate - Source charge	Q _{gs} *3	I _D = 10A	-	7	-	nC
Gate - Drain charge	Q _{gd} *3	V _{GS} = 10V	-	6.5	-	
Gate plateau voltage	V _(plateau)	$V_{DD} \simeq 300V$, $I_D = 10A$	-	6.4	-	V

*1 Limited only by maximum temperature allowed.

*2 Pw \leq 10µs, Duty cycle \leq 1%

*3 L=500 μ H, VDD=50V, RG=25 Ω , STARTING Tch=25°C, See Fig.3-1,3-2

*4 Tc=25°C

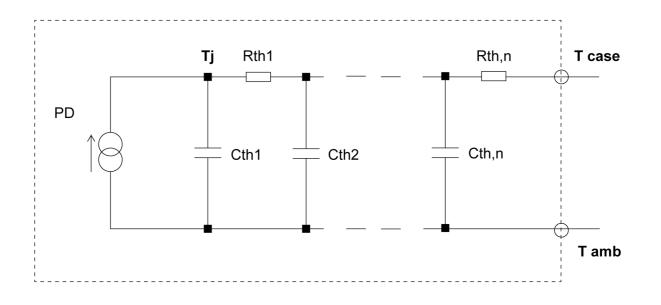


•Body diode electrical characteristics (Source-Drain) (T_a = 25°C)

Parameter	Sympol	Conditions	Values			Unit	
	Symbol	Conditions	Min.	Тур.	Max.	Unit	
Continuous forward current	۱ _S *1	T - 25°0	-	-	10	А	
Pulse forward current	ا _{SP} *2	T _C = 25°C	-	-	30	А	
Forward voltage	V _{SD} *3	V _{GS} = 0V, I _S = 10A	-	-	1.5	V	
Reverse recovery time	t _{rr} *3		50	80	110	ns	
Reverse recovery charge	Q _{rr} *3	I _S = 10A di/dt = 100A/µs	140	280	385	nC	
Peak reverse recovery current	۲ _{rm} *3		-	-	-	А	

• Typical transient thermal characteristics

Symbol	Value	Unit	Symbol	Value	Unit
R _{th1}	0.2503		C _{th1}	0.004105	
R _{th2}	3.395		C _{th2}	0.04901	
R _{th3}	26.12	K/W	C _{th3}	0.1984	Ws/K
R _{th4}	56.72		C _{th4}	0.3826	1





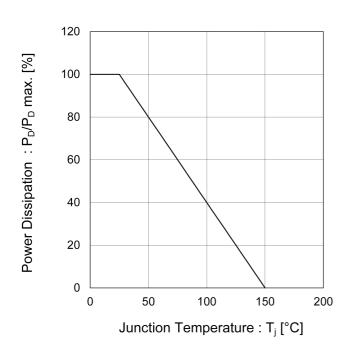


Fig.1 Power Dissipation Derating Curve

Fig.2 Maximum Safe Operating Area

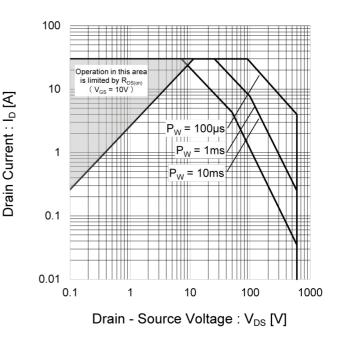
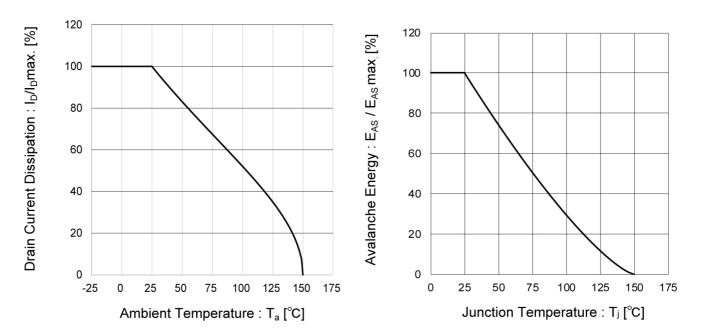


Fig.3 Drain Current Derating Curve vs. Ambient Temperature

Fig.4 Avalanche Energy Derating Curve vs. Junction Temperature





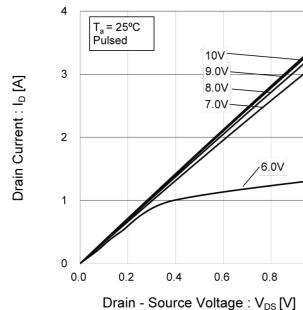
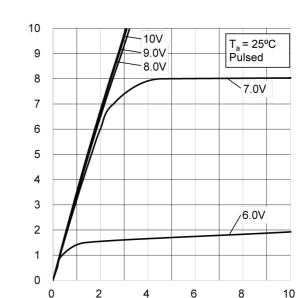


Fig.5 Typical Output Characteristics(I)



Drain Current : I_D [A]

1.0

Fig.6 Typical Output Characteristics(II)

Drain - Source Voltage : V_{DS} [V]

Fig.7 Normalized Breakdown Voltage vs. Junction Temperature

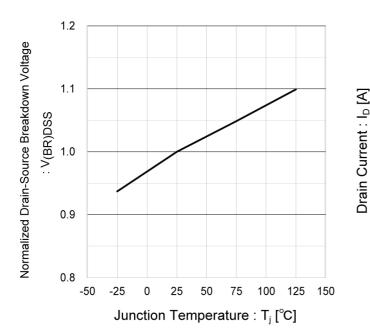
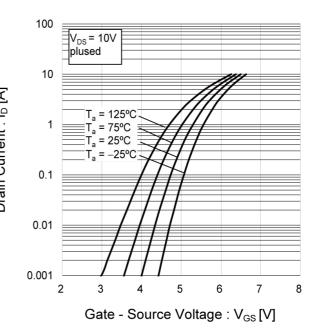


Fig.8 Typical Transfer Characteristics





100

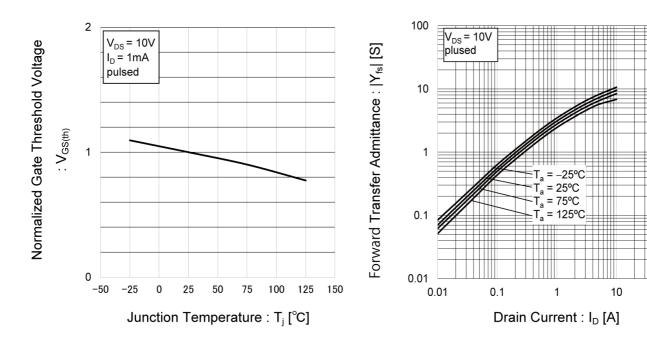


Fig.9 Normalized Gate Threshold Voltage. vs Junction Temperature

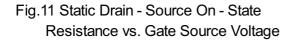


Fig.12 Normalized Static Drain - Source On - State Resistance vs. Junction Temperature

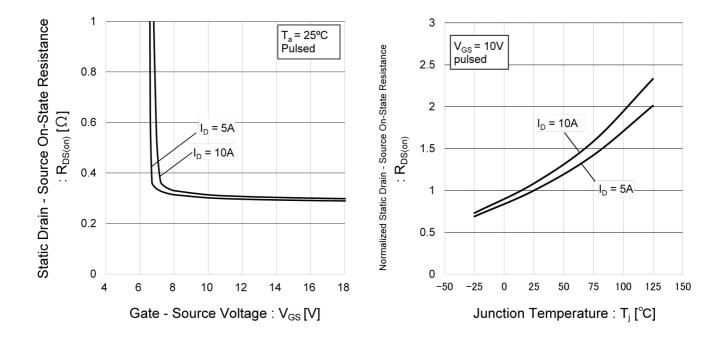


Fig.10 Forward Transfer Admittance vs. Drain Current



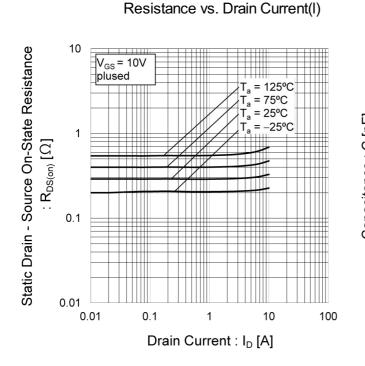


Fig.13 Static Drain - Source On - State

Fig.14 Typical Capacitance vs. Drain - Source Voltage

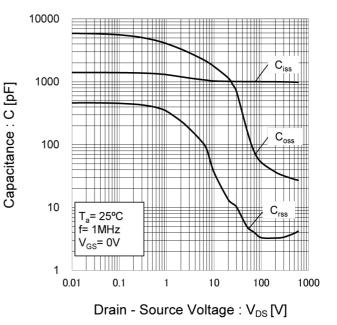
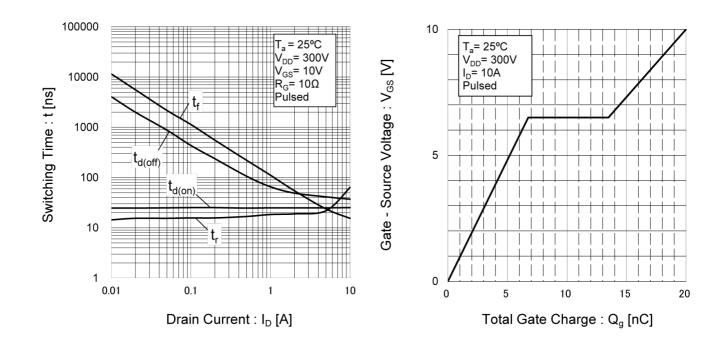


Fig.15 Switching Characteristics

Fig.16 Dynamic Input Characteristics





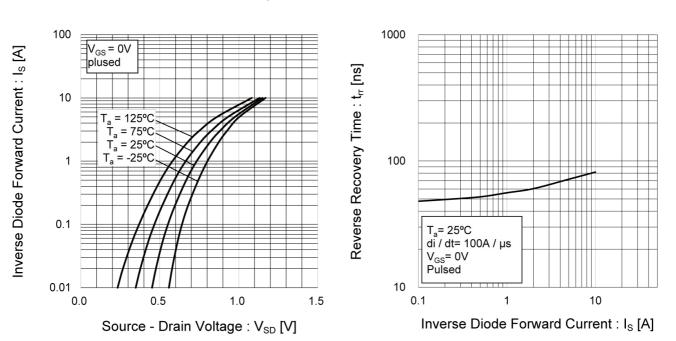
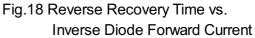


Fig.17 Inverse Diode Forward Current vs. Source - Drain Voltage





Measurement circuits

Fig.1-1 Switching Time Measurement Circuit

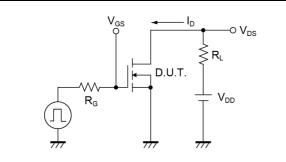


Fig.2-1 Gate Charge Measurement Circuit

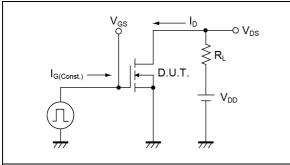


Fig.3-1 Avalanche Measurement Circuit

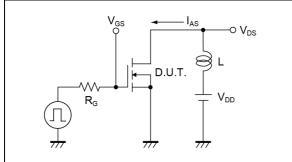


Fig.4-1 dv/dt Measurement Circuit

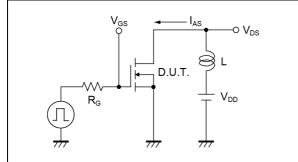


Fig.5-1 di/dt Measurement Circuit

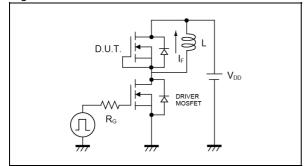


Fig.1-2 Switching Waveforms

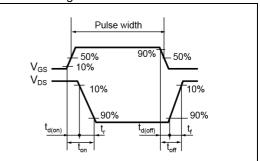


Fig.2-2 Gate Charge Waveform

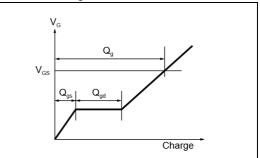


Fig.3-2 Avalanche Waveform

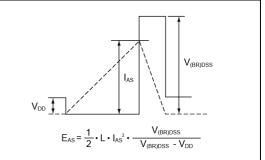


Fig.4-2 dv/dt Waveform

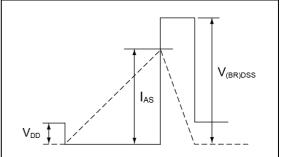
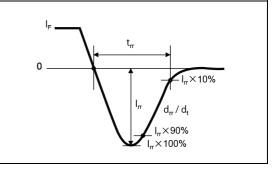
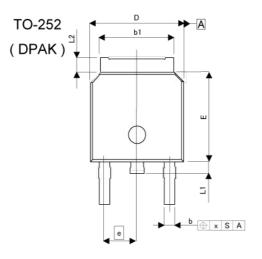


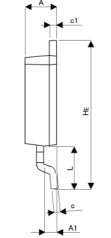
Fig.5-2 di/dt Waveform

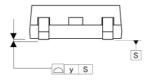


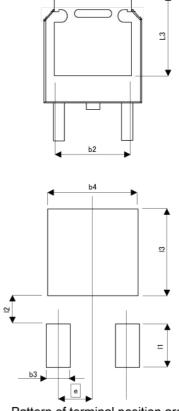


Dimensions









Pattern of terminal position areas [Not a pattern of soldering pads]

DIM	MILIME	TERS	INC	HES
DIVI	MIN	MAX	MIN	MAX
A	2.10	2.30	0.083	0.091
A1	0.70	1.10	0.028	0.043
b	0.65	0.85	0.026	0.033
b1	5.10	5.40	0.201	0.213
b2	5.	10	0.2	201
С	0.40	0.60	0.016	0.024
c1	0.40	0.60	0.016	0.024
D	6.40	6.80	0.252	0.268
е	2.	30	0.0)91
E	6.00	6.40	0.236	0.252
HE	9.50	10.50	0.374	0.413
L	2.	90	0.1	14
L1	0.70	0.90	0.028	0.035
L2	0.70	1.30	0.028	0.051
L3	5.	30	0.209	
х	-	0.10	-	0.004
у	-	0.10	-	0.004
		TEDO	IN CO	
DIM		TERS		HES
10	MIN	MAX	MIN	MAX
b3	-	1.10	-	0.043
b4	-	5.40	-	0.213
1		90)35
12		00	0.079	
13	5.30		0.2	209

Dimension in mm/inches



Notice

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1. Our Products are designed and manufactured for application in ordinary electronic equipments (such as AV equipment, OA equipment, telecommunication equipment, home electronic appliances, amusement equipment, etc.). If you intend to use our Products in devices requiring extremely high reliability (such as medical equipment ^(Note 1), transport equipment, traffic equipment, aircraft/spacecraft, nuclear power controllers, fuel controllers, car equipment including car accessories, safety devices, etc.) and whose malfunction or failure may cause loss of human life, bodily injury or serious damage to property ("Specific Applications"), please consult with the ROHM sales representative in advance. Unless otherwise agreed in writing by ROHM in advance, ROHM shall not be in any way responsible or liable for any damages, expenses or losses incurred by you or third parties arising from the use of any ROHM's Products for Specific Applications.

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CLASSⅣ	CLASSII	CLASSⅢ	CLASSI

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 - [b] Installation of redundant circuits to reduce the impact of single or multiple circuit failure
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 - [b] Use of our Products outdoors or in places where the Products are exposed to direct sunlight or dust
 - [c] Use of our Products in places where the Products are exposed to sea wind or corrosive gases, including Cl₂, H₂S, NH₃, SO₂, and NO₂
 - [d] Use of our Products in places where the Products are exposed to static electricity or electromagnetic waves
 - [e] Use of our Products in proximity to heat-producing components, plastic cords, or other flammable items
 - [f] Sealing or coating our Products with resin or other coating materials
 - [g] Use of our Products without cleaning residue of flux (even if you use no-clean type fluxes, cleaning residue of flux is recommended); or Washing our Products by using water or water-soluble cleaning agents for cleaning residue after soldering
 - [h] Use of the Products in places subject to dew condensation
- 4. The Products are not subject to radiation-proof design.
- 5. Please verify and confirm characteristics of the final or mounted products in using the Products.
- 6. In particular, if a transient load (a large amount of load applied in a short period of time, such as pulse. is applied, confirmation of performance characteristics after on-board mounting is strongly recommended. Avoid applying power exceeding normal rated power; exceeding the power rating under steady-state loading condition may negatively affect product performance and reliability.
- 7. De-rate Power Dissipation depending on ambient temperature. When used in sealed area, confirm that it is the use in the range that does not exceed the maximum junction temperature.
- 8. Confirm that operation temperature is within the specified range described in the product specification.
- 9. ROHM shall not be in any way responsible or liable for failure induced under deviant condition from what is defined in this document.

Precaution for Mounting / Circuit board design

- 1. When a highly active halogenous (chlorine, bromine, etc.) flux is used, the residue of flux may negatively affect product performance and reliability.
- 2. In principle, the reflow soldering method must be used on a surface-mount products, the flow soldering method must be used on a through hole mount products. If the flow soldering method is preferred on a surface-mount products, please consult with the ROHM representative in advance.

For details, please refer to ROHM Mounting specification

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- 1. If change is made to the constant of an external circuit, please allow a sufficient margin considering variations of the characteristics of the Products and external components, including transient characteristics, as well as static characteristics.
- 2. You agree that application notes, reference designs, and associated data and information contained in this document are presented only as guidance for Products use. Therefore, in case you use such information, you are solely responsible for it and you must exercise your own independent verification and judgment in the use of such information contained in this document. ROHM shall not be in any way responsible or liable for any damages, expenses or losses incurred by you or third parties arising from the use of such information.

Precaution for Electrostatic

This Product is electrostatic sensitive product, which may be damaged due to electrostatic discharge. Please take proper caution in your manufacturing process and storage so that voltage exceeding the Products maximum rating will not be applied to Products. Please take special care under dry condition (e.g. Grounding of human body / equipment / solder iron, isolation from charged objects, setting of lonizer, friction prevention and temperature / humidity control).

Precaution for Storage / Transportation

- 1. Product performance and soldered connections may deteriorate if the Products are stored in the places where:
 - [a] the Products are exposed to sea winds or corrosive gases, including Cl2, H2S, NH3, SO2, and NO2
 - [b] the temperature or humidity exceeds those recommended by ROHM
 - [c] the Products are exposed to direct sunshine or condensation
 - [d] the Products are exposed to high Electrostatic
- 2. Even under ROHM recommended storage condition, solderability of products out of recommended storage time period may be degraded. It is strongly recommended to confirm solderability before using Products of which storage time is exceeding the recommended storage time period.
- 3. Store / transport cartons in the correct direction, which is indicated on a carton with a symbol. Otherwise bent leads may occur due to excessive stress applied when dropping of a carton.
- 4. Use Products within the specified time after opening a humidity barrier bag. Baking is required before using Products of which storage time is exceeding the recommended storage time period.

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R6010MND3 - Web Page

Part Number	R6010MND3
Package	TO-252
Unit Quantity	2500
Minimum Package Quantity	2500
Packing Type	Taping
Constitution Materials List	inquiry
RoHS	Yes